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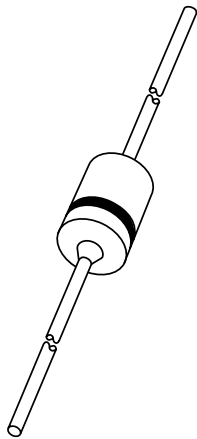
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DISCRETE SEMICONDUCTORS

DATA SHEET



1N914; 1N914A; 1N914B High-speed diodes

Product specification
 Supersedes data of 1999 May 26

2003 Jun 06

High-speed diodes

1N914; 1N914A; 1N914B

FEATURES

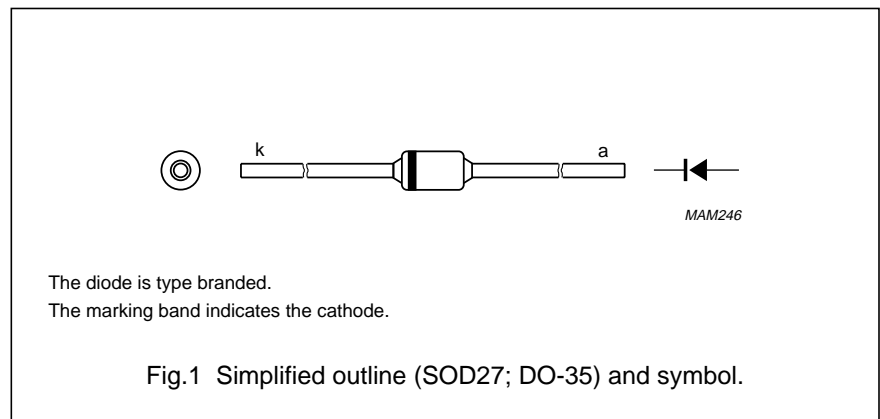
- Hermetically sealed leaded glass SOD27 (DO-35) package
- High switching speed: max. 4 ns
- Continuous reverse voltage: max. 75 V
- Repetitive peak reverse voltage: max. 100 V
- Repetitive peak forward current: max. 225 mA.

APPLICATIONS

- High-speed switching.

DESCRIPTION

The 1N914, 1N914A and 1N914B are high-speed switching diodes fabricated in planar technology, and encapsulated in a hermetically sealed leaded glass SOD27 (DO-35) package.



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{RRM}	repetitive peak reverse voltage		–	100	V
V_R	continuous reverse voltage		–	75	V
I_F	continuous forward current	see Fig.2; note 1	–	75	mA
I_{FRM}	repetitive peak forward current		–	225	mA
I_{FSM}	non-repetitive peak forward current	square wave; $T_j = 25\text{ °C}$ prior to surge; see Fig.4			
		$t = 1\ \mu\text{s}$	–	4	A
		$t = 1\ \text{ms}$	–	1	A
		$t = 1\ \text{s}$	–	0.5	A
P_{tot}	total power dissipation	$T_{amb} = 25\text{ °C}$; note 1	–	250	mW
T_{stg}	storage temperature		–65	+200	°C
T_j	junction temperature		–	175	°C

Note

1. Device mounted on an FR4 printed-circuit board; lead length 10 mm.

High-speed diodes

1N914; 1N914A; 1N914B

ELECTRICAL CHARACTERISTICS

$T_j = 25\text{ °C}$; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_F	forward voltage	see Fig.3			
	1N914; 1N914A	$I_F = 10\text{ mA}$	–	1	V
	1N914B	$I_F = 5\text{ mA}$	0.62	0.72	V
	1N914B	$I_F = 100\text{ mA}$	–	1	V
I_R	reverse current	see Fig.5			
		$V_R = 20\text{ V}$	–	25	nA
		$V_R = 75\text{ V}$	–	5	μA
		$V_R = 20\text{ V}; T_j = 150\text{ °C}$	–	50	μA
C_d	diode capacitance	$f = 1\text{ MHz}; V_R = 0$; see Fig.6	–	4	pF
t_{rr}	reverse recovery time	when switched from $I_F = 10\text{ mA}$ to $I_R = 10\text{ mA}$; $R_L = 100\ \Omega$; measured at $I_R = 1\text{ mA}$; see Fig.7	–	8	ns
		when switched from $I_F = 10\text{ mA}$ to $I_R = 60\text{ mA}$; $R_L = 100\ \Omega$; measured at $I_R = 1\text{ mA}$; see Fig.7	–	4	ns
V_{fr}	forward recovery voltage	when switched from $I_F = 50\text{ mA}$; $t_r = 20\text{ ns}$; see Fig.8	–	2.5	V

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-tp}$	thermal resistance from junction to tie-point	lead length 10 mm	240	K/W
$R_{th\ j-a}$	thermal resistance from junction to ambient	lead length 10 mm; note 1	500	K/W

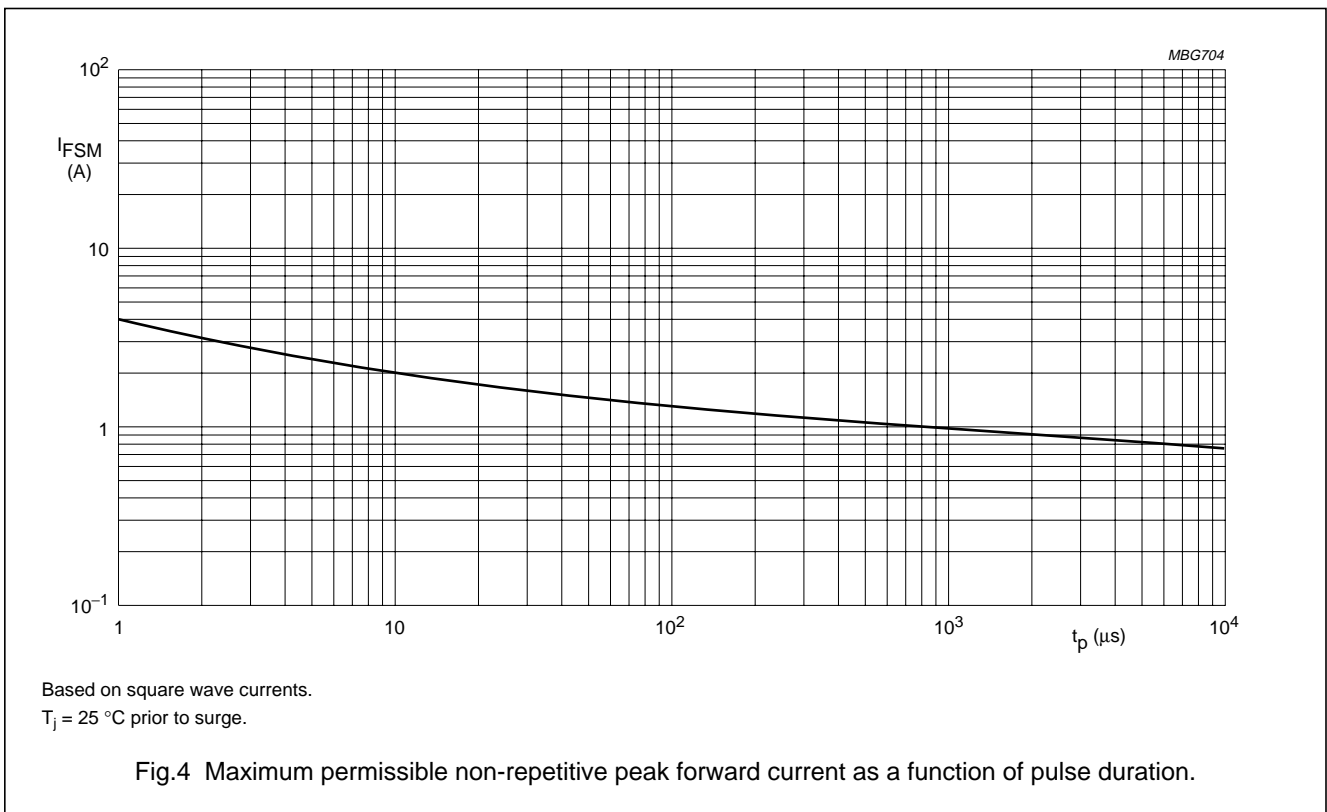
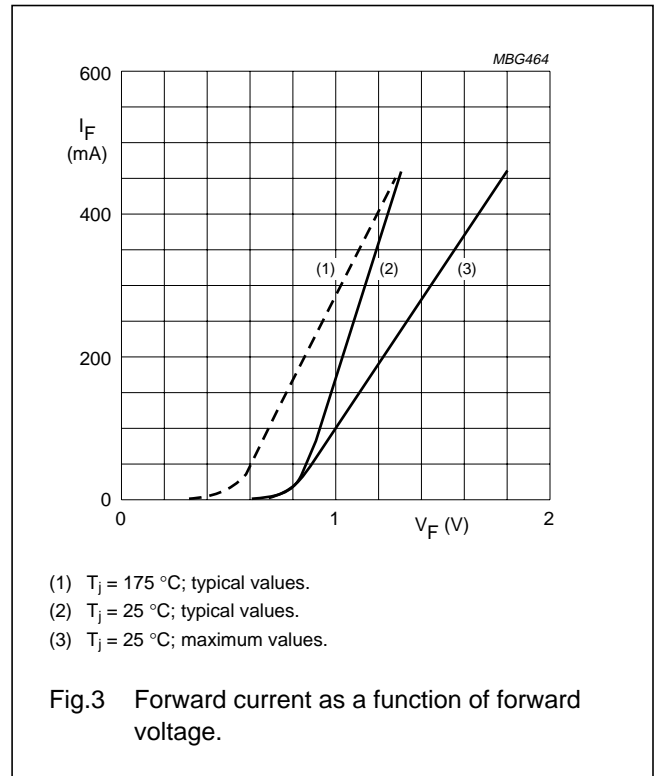
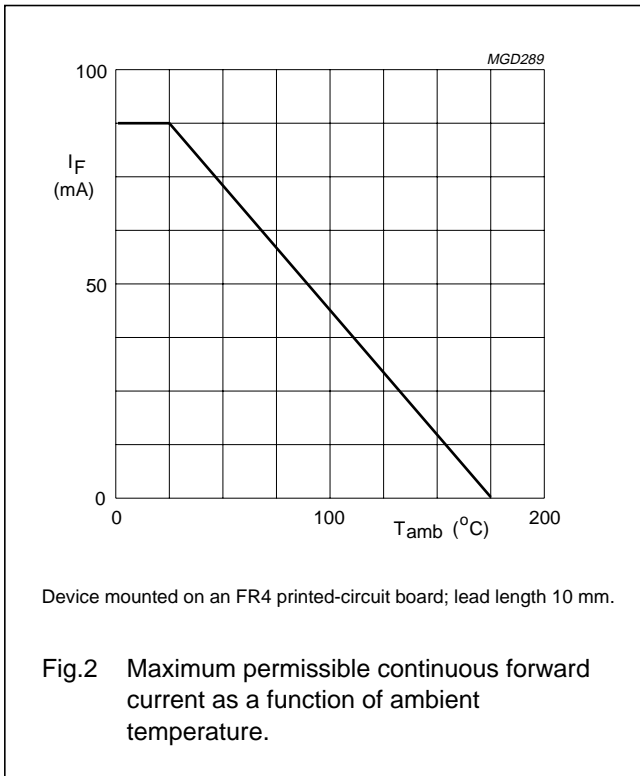
Note

1. Device mounted on a printed-circuit board without metallization pad.

High-speed diodes

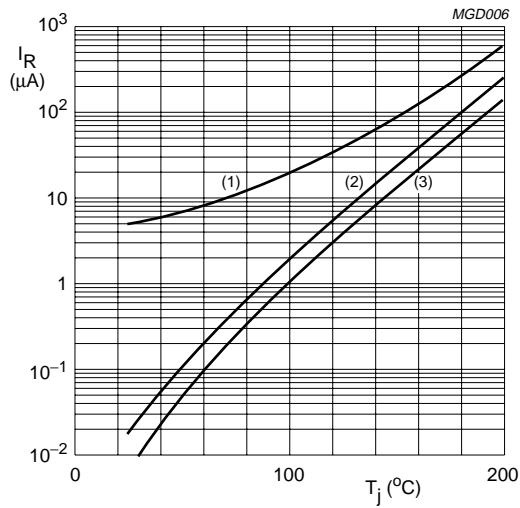
1N914; 1N914A; 1N914B

GRAPHICAL DATA



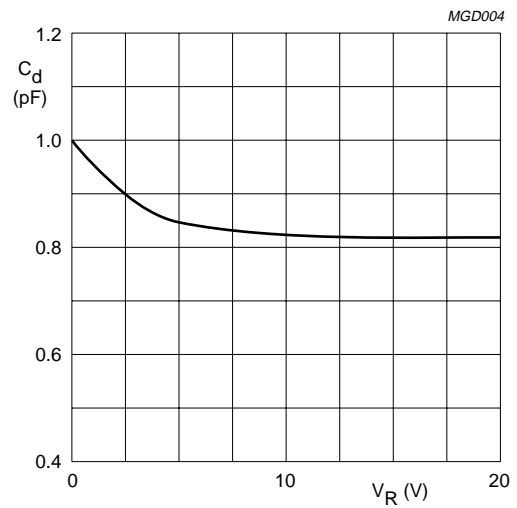
High-speed diodes

1N914; 1N914A; 1N914B



- (1) $V_R = 75\text{ V}$; maximum values.
- (2) $V_R = 75\text{ V}$; typical values.
- (3) $V_R = 20\text{ V}$; typical values.

Fig.5 Reverse current as a function of junction temperature.

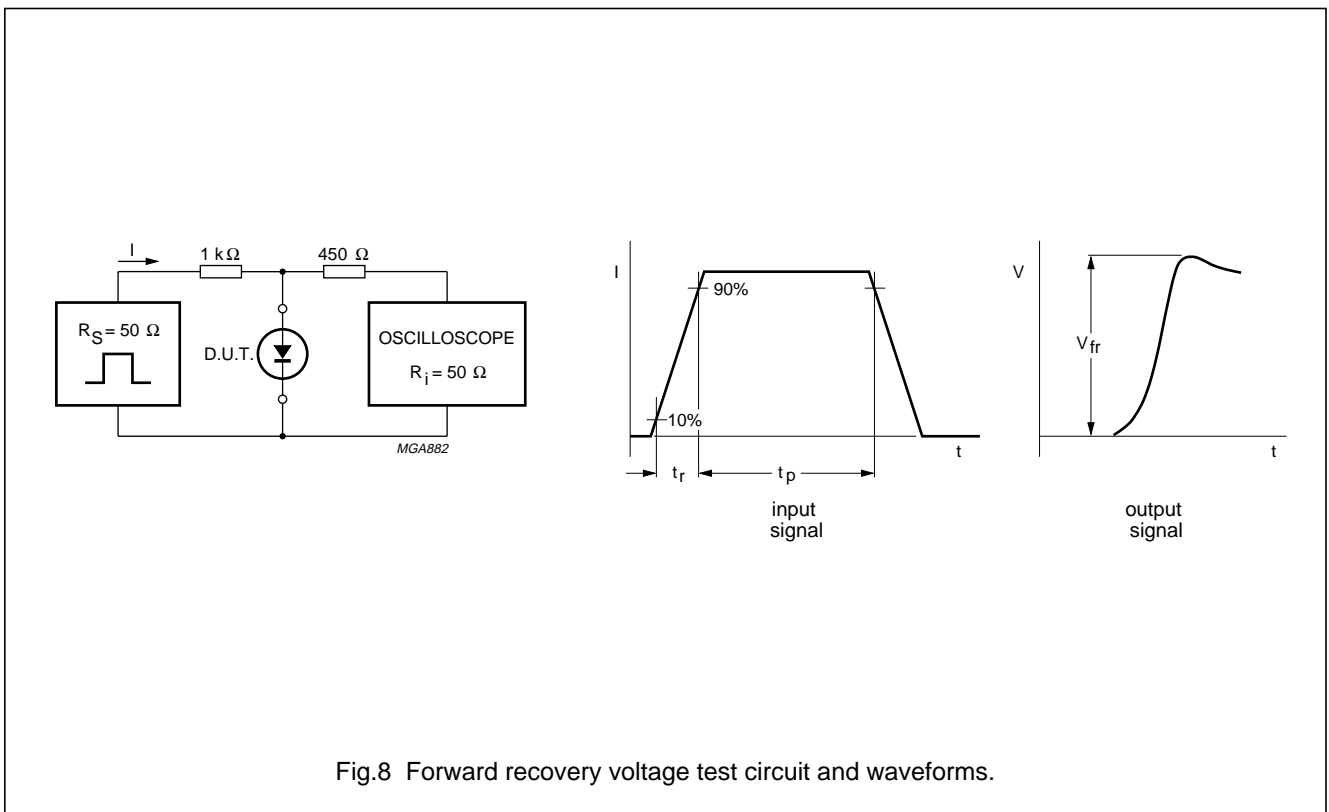
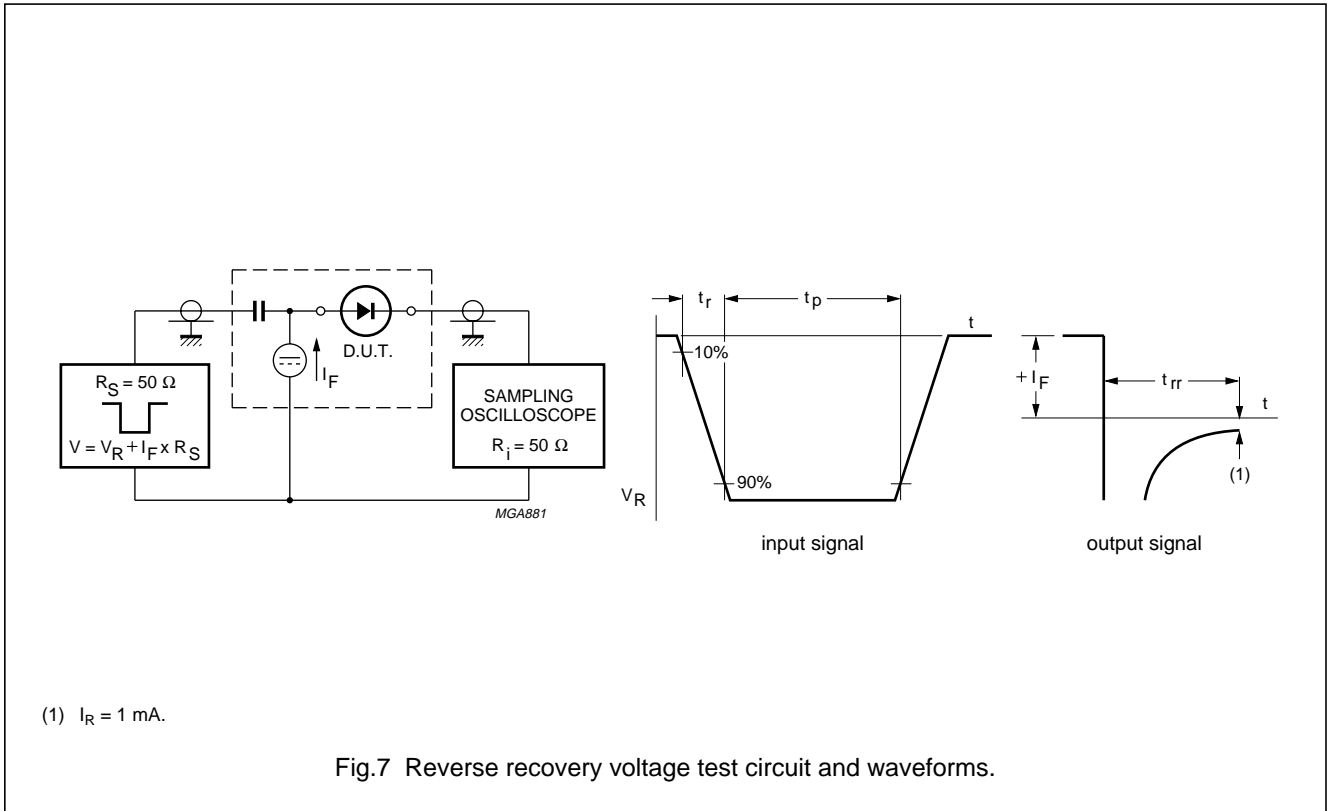


$f = 1\text{ MHz}$; $T_j = 25\text{ °C}$.

Fig.6 Diode capacitance as a function of reverse voltage; typical values.

High-speed diodes

1N914; 1N914A; 1N914B



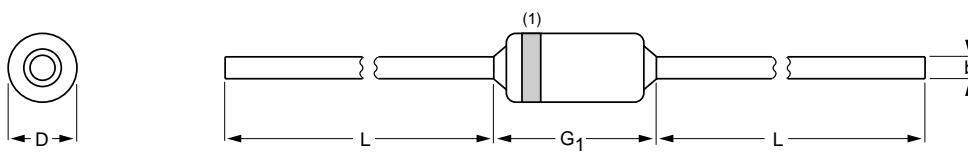
High-speed diodes

1N914; 1N914A; 1N914B

PACKAGE OUTLINE

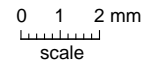
Hermetically sealed glass package; axial leaded; 2 leads

SOD27



DIMENSIONS (mm are the original dimensions)

UNIT	b max.	D max.	G ₁ max.	L min.
mm	0.56	1.85	4.25	25.4



Note

1. The marking band indicates the cathode.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOD27	A24	DO-35	SC-40			97-06-09

High-speed diodes

1N914; 1N914A; 1N914B

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾⁽³⁾	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
III	Product data	Production	This data sheet contains data from the product specification. Philips Semiconductors reserves the right to make changes at any time in order to improve the design, manufacturing and supply. Relevant changes will be communicated via a Customer Product/Process Change Notification (CPCN).

Notes

1. Please consult the most recently issued data sheet before initiating or completing a design.
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3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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High-speed diodes

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NOTES

High-speed diodes

1N914; 1N914A; 1N914B

NOTES

High-speed diodes

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NOTES

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Printed in The Netherlands

613514/04/pp12

Date of release: 2003 Jun 06

Document order number: 9397 750 11511

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